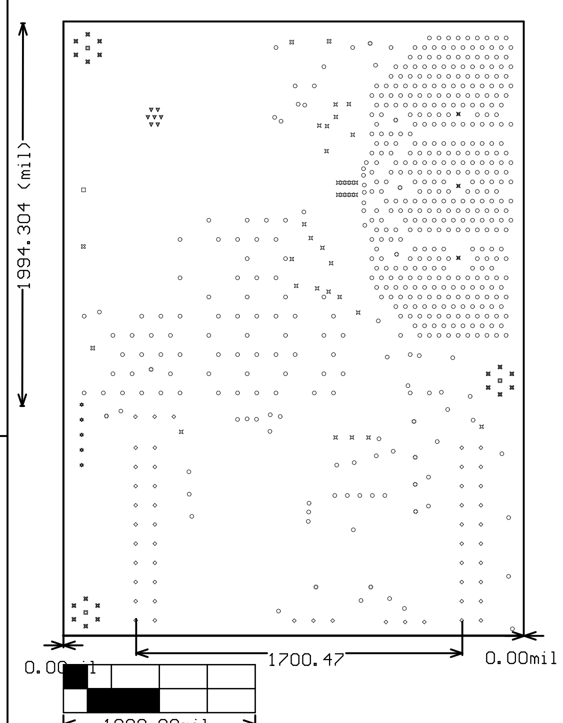
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.20mil		
	Dielectric 1	FR-4	8.00mil	4.2	
2	Ground		1.40mil		
	Dielectric	FR-4	40.00mil	4.2	
3	Power		1.40mil		
	Dielectric 2	FR-4	8.00mil	4.2	
4	Bottom Layer		1.20mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
	7	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
	32	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
	519	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
	18	19.69mil (0.500mm)	PTH	Round	Top Layer - Bottom Layer	
	5	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
	12	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
	49	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
	3	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
	1	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	3	92.52mil (2.350mm)	PTH	Round	Top Layer - Bottom Layer	
	4	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	
	653 Total					

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 7.874 MIL

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-4 [x] FR-4 High Tg [ ] OTHER ______

THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [x] OTHER 68 MIL +/-10%

TOLERANCE: [x] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- ______

BOW & TWIST: [x] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- ______

DRILLING:

REFERENCE: [x] AS SHOWN [x] NC_DRILL FILES

PTH COPPER THICKNESS: [x] 20-30 um [ ] OTHER ______

BOARD FINISH:

SILKSCREEN: [x] TOP [x] BOTTOM

SILKSCREEN COLOR: [x] WHITE [ ] OTHER ______

SOLDER RESIST COLOR: [x] GREEN [ ] OTHER ______
[ ] MATTE [x] SEMI-GLOSS

SURFACE FINISH: [x] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER ______

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [x] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[x] ANSI IPC-A-600F CLASS -> [ ] 1 [x] 2 [ ] 3
[x] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [x] REQUIRED [ ] PER ORDER

[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: DRV8374EVM

DESIGNED FOR: Public Release

FILE NAME: MD106.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: MD106 | REV: A | SVN REV: Not in version control

LAYER NAME = M9 Title Sheet

TID #: N/A

PLOT NAME = Fabrication Drawing

GENERATED : 4/23/2026 1:15:50 PM | TEXAS INSTRUMENTS

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ENGINEER: Yara Al-Shami

LAYOUT BY: Yara Al-Shami

SCALE: 1.00

ALTIUM DESIGNER VERSION: 23.1.1.15